

ABSTRACT OF THE DISCLOSURE

APPARATUS FOR LIQUID TREATMENT OF WAFER SHAPED ARTICLES

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An apparatus for processing wafer-shaped articles comprises a spin chuck adapted to hold and spin a wafer-shaped article of a predetermined diameter during a processing operation. A liquid collector surrounds the spin
10 chuck, and comprises a first inner surface. The first inner surface comprises a first conductive material. The collector further comprises a first conductive pathway for grounding the first conductive material.

15 Fig. 1